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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10008704	FILING DATE 12/06/2001	CLASS 357	SUBCLASS 678	GAU 2825 2842	EXAMINER Tran, Tan
<b>**APPLICANTS:</b> Ahn Sang-Ho; Oh Se-Yong;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> REPUBLIC OF KOREA 2001-11182 03/05/2001 REPUBLIC OF KOREA 2001-38717 06/30/2001					
PGPUB DO NOT PUBLISH <input type="checkbox"/>		RES <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 9903-045			
Verified and Acknowledged Examiners's initials					
TITLE : Ultra-thin semiconductor package device and method for manufacturing the same <small>U.S. DEPT. OF COMM./PAT. &amp; TM.-PTO-436 (Rev. 12-94)</small>					

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NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
				Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner		DRAWING	
Amount Due	Date Paid			Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner	
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